



PC Board Layout
Component Side Shown

NOTES:

MATERIAL :

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
- 2.CONTACT MATERIAL :PHOSPHOR BRONZE φ0.46mm.
- 3.PLATING :GOLD PLATING OVER NICKEL.
- 4.SHIELD :0.23mm THICKNESS COPPER ALLOY WITH NICKEL PLATED.

ELECTRICAL:

- 1.VOLTAGE RATING :125 VAC RMS.
- 2.CURRENT RATING :15 AMP.
- 3.CONTACT RESISTANCE :50 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC .
- 5.DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1.DURRABILITY :750 CYCLES MIN.
- 2.PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

- 1.STORAGE : -40℃~+85℃
- 2.OPERATION : 0℃ TO 70℃.

<p>RoHS Compliant</p>		<p>HSM 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.</p>	
<p>APPD. 核准</p>		<p>TOLERANCE 容許公差</p>	<p>PART NAME 品名</p>
<p>DWG. 製圖</p>	<p>SCALE 比例</p>	<p>.0 ± 0.30 .00 ± 0.20 ANG. ± 3°</p>	<p>STACKED PCB JACK ROUND PIN 8P8C 2X6P GANG TYPE SHIELDED BLACK COLOR ROHS</p>
<p>DATE 制表日</p>	<p>UNIT 單位</p>	<p>M M</p>	<p>PART NO.</p>
<p>2015/09/07</p>	<p>PAGE 張數</p>	<p>1 OF 1</p>	<p>料號 C0061-88LYXB00R</p>
<p>Betty</p>	<p>參考</p>	<p>SIZE. 紙張尺寸</p>	<p>A 4</p>
<p>REV. 版次</p>	<p>A</p>	<p>REV. 版次</p>	<p>A</p>